

ABSTRACT

A resin plating method for a resin molding is disclosed which involves a simple process as an additional process in resin plating to suppress the occurrence of such an undesirable phenomenon as a metal plating film peeling together with a thin resin film due to floating of a thin surface film of the resin molding. A specific portion of the resin molding which portion is apt to undergo peeling of a thin surface resin film is heat-treated at a high temperature and thereafter resin plating is performed.